

## Dual Bidirectional I<sup>2</sup>C Bus and SMBus Repeater

### 1 Features

- Two-Channel Bidirectional Buffers
- I<sup>2</sup>C Bus and SMBus Compatible
- Active-High Repeater-Enable Input
- Open-Drain I<sup>2</sup>C I/O
- 5.5-V Tolerant I<sup>2</sup>C I/O and Enable Input Support Mixed-Mode Signal Operation
- Lockup-Free Operation
- Accommodates Standard Mode and Fast Mode I<sup>2</sup>C Devices and Multiple Masters
- Powered-Off High-Impedance I<sup>2</sup>C Pins
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)
  - 1000-V Charged-Device Model (C101)

### 2 Description

This dual bidirectional I<sup>2</sup>C buffer is operational at 2.3-V to 3.6-V V<sub>CC</sub>.

The PCA9515A is a BiCMOS integrated circuit intended for I<sup>2</sup>C bus and SMBus systems applications. The device contains two identical bidirectional open-drain buffer circuits that enable I<sup>2</sup>C and similar bus systems to be extended without degradation of system performance.

The PCA9515A buffers both the serial data (SDA) and serial clock (SCL) signals on the I<sup>2</sup>C bus, while retaining all the operating modes and features of the I<sup>2</sup>C system. This enables two buses of 400-pF bus capacitance to be connected in an I<sup>2</sup>C application.

The I<sup>2</sup>C bus capacitance limit of 400 pF restricts the number of devices and bus length. Using the PCA9515A enables the system designer to isolate two halves of a bus, accommodating more I<sup>2</sup>C devices or longer trace lengths.

The PCA9515A has an active-high enable (EN) input with an internal pullup, which allows the user to select when the repeater is active. This can be used to isolate a badly behaved slave on power-up reset. It never should change state during an I<sup>2</sup>C operation, because disabling during a bus operation hangs the bus, and enabling part way through a bus cycle could confuse the I<sup>2</sup>C parts being enabled. The EN input should change state only when the global bus and the repeater port are in an idle state, to prevent system failures.

The PCA9515A also can be used to run two buses: one at 5-V interface levels and the other at 3.3-V interface levels, or one at 400-kHz operating frequency and the other at 100-kHz operating frequency. If the two buses are operating at different frequencies, the 100-kHz bus must be isolated when the 400-kHz operation of the other bus is required. If the master is running at 400 kHz, the maximum system operating frequency may be less than 400 kHz, because of the delays that are added by the repeater.

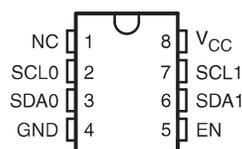
The PCA9515A does not support clock stretching across the repeater.

#### Device Information<sup>(1)</sup>

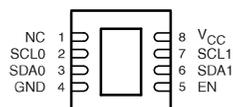
PART NUMBER	PACKAGE	BODY SIZE (NOM)
PCA9515A	SOIC (8)	4.90 mm × 3.91 mm
	SON (8)	3.00 mm × 3.00 mm

(1) For all available packages, see the orderable addendum at the end of the datasheet.

D, DCT, DGK, OR PW PACKAGE  
(TOP VIEW)



DRG PACKAGE  
(TOP VIEW)



NC – No internal connection



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### 3 Revision History

Changes from Revision C (January 2011) to Revision D	Page
<ul style="list-style-type: none"> <li>• Added Clock Stretching Errata section. .... 7</li> </ul>	7
Changes from Revision B (October 2007) to Revision C	Page
<ul style="list-style-type: none"> <li>• Deleted all references to arbitration and clock stretching support. This does not effect min/max specifications. .... 1</li> </ul>	1

## 4 Description (Continued)

The output low levels for each internal buffer are approximately 0.5 V, but the input voltage of each internal buffer must be 70 mV or more below the output low level, when the output internally is driven low. This prevents a lockup condition from occurring when the input low condition is released.

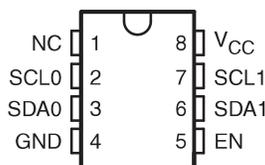
Two or more PCA9515A devices cannot be used in series. The PCA9515A design does not allow this configuration. Because there is no direction pin, slightly different valid low-voltage levels are used to avoid lockup conditions between the input and the output of each repeater. A valid low applied at the input of a PCA9515A is propagated as a buffered low with a slightly higher value on the enabled outputs. When this buffered low is applied to another PCA9515A-type device in series, the second device does not recognize it as a valid low and does not propagate it as a buffered low again.

The device contains a power-up control circuit that sets an internal latch to prevent the output circuits from becoming active until  $V_{CC}$  is at a valid level ( $V_{CC} = 2.3$  V).

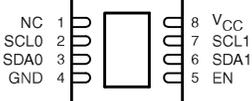
As with the standard I<sup>2</sup>C system, pullup resistors are required to provide the logic high levels on the buffered bus. The PCA9515A has standard open-collector configuration of the I<sup>2</sup>C bus. The size of these pullup resistors depends on the system, but each side of the repeater must have a pullup resistor. The device is designed to work with Standard Mode and Fast Mode I<sup>2</sup>C devices in addition to SMBus devices. Standard Mode I<sup>2</sup>C devices only specify 3 mA in a generic I<sup>2</sup>C system where Standard Mode devices and multiple masters are possible. Under certain conditions, high termination currents can be used.

## 5 Pin Configuration and Functions

D, DCT, DGK, OR PW PACKAGE  
(TOP VIEW)



DRG PACKAGE  
(TOP VIEW)



NC – No internal connection

### Pin Functions

PIN		DESCRIPTION
NAME	NO.	
NC	1	No internal connection
SCL0	2	Serial clock bus 0
SDA0	3	Serial data bus 0
GND	4	Supply ground
EN	5	Active-high repeater enable input
SDA1	6	Serial data bus 1
SCL1	7	Serial clock bus 1
$V_{CC}$	8	Supply power

## 6 Specifications

### 6.1 Absolute Maximum Ratings<sup>(1)</sup>

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage range	–0.5	7	V
V <sub>I</sub>	Enable input voltage range <sup>(2)</sup>	–0.5	7	V
V <sub>I/O</sub>	I <sup>2</sup> C bus voltage range <sup>(2)</sup>	–0.5	7	V
I <sub>IK</sub>	Input clamp current	V <sub>I</sub> < 0	–50	mA
I <sub>OK</sub>	Output clamp current	V <sub>O</sub> < 0	–50	mA
I <sub>O</sub>	Continuous output current		±50	mA
	Continuous current through V <sub>CC</sub> or GND		±100	mA
θ <sub>JA</sub>	Package thermal impedance <sup>(3)</sup>	D package	97	°C/W
		DCT package	220	
		DGK package	172	
		DRG package	TBD	
		PW package	149	

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) The package thermal impedance is calculated in accordance with JESD 51-7.

### 6.2 Handling Ratings

		MIN	MAX	UNIT	
T <sub>stg</sub>	Storage temperature range	–65	150	°C	
V <sub>(ESD)</sub>	Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001, all pins <sup>(1)</sup>	0	2000	V
		Charged device model (CDM), per JEDEC specification JESD22-C101, all pins <sup>(2)</sup>	0	1000	

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
- (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

### 6.3 Recommended Operating Conditions

		MIN	MAX	UNIT	
V <sub>CC</sub>	Supply voltage	2.3	3.6	V	
V <sub>IH</sub>	High-level input voltage	SDA and SCL inputs	0.7 × V <sub>CC</sub>	5.5	V
		EN input	2	5.5	
V <sub>IL</sub> <sup>(1)</sup>	Low-level input voltage	SDA and SCL inputs	–0.5	0.3 × V <sub>CC</sub>	V
		EN input	–0.5	0.8	
V <sub>ILc</sub> <sup>(1)</sup>	SDA and SCL low-level input voltage contention	–0.5	0.4	V	
I <sub>OL</sub>	Low-level output current	V <sub>CC</sub> = 2.3 V	6	mA	
		V <sub>CC</sub> = 3 V	6		
T <sub>A</sub>	Operating free-air temperature	–40	85	°C	

- (1) V<sub>IL</sub> specification is for the EN input and the first low level seen by the SDAx and SCLx lines. V<sub>ILc</sub> is for the second and subsequent low levels seen by the SDAx and SCLx lines. V<sub>ILc</sub> must be at least 70 mV below V<sub>OL</sub>.

## 6.4 Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V <sub>CC</sub>	MIN	TYP <sup>(1)</sup>	MAX	UNIT		
V <sub>IK</sub>	Input diode clamp voltage	I <sub>I</sub> = –18 mA	2.3 V to 3.6 V			–1.2	V		
V <sub>OL</sub>	Low-level output voltage	SDA <sub>x</sub> , SCL <sub>x</sub> I <sub>OL</sub> = 20 μA or 6 mA	2.3 V to 3.6 V	0.47	0.52	0.6	V		
V <sub>OL</sub> – V <sub>ILc</sub>	Low-level input voltage below low-level output voltage	SDA <sub>x</sub> , SCL <sub>x</sub> I <sub>I</sub> = 10 μA	2.3 V to 3.6 V			70	mV		
I <sub>CC</sub>	Quiescent supply current	Both channels high, SDA <sub>x</sub> = SCL <sub>x</sub> = V <sub>CC</sub>	2.7 V		0.5	3	mA		
			3.6 V		0.5	3			
		Both channels low, SDA0 = SCL0 = GND and SDA1 = SCL1 = open; or SDA0 = SCL0 = open and SDA1 = SCL1 = GND	2.7 V		1	4			
			3.6 V		1	4			
In contention, SDA <sub>x</sub> = SCL <sub>x</sub> = GND	2.7 V		1	4					
	3.6 V		1	4					
I <sub>I</sub>	Input current	SDA <sub>x</sub> , SCL <sub>x</sub>	V <sub>I</sub> = 3.6 V	2.3 V to 3.6 V			±1	μA	
			V <sub>I</sub> = 0.2 V				3		
		EN	V <sub>I</sub> = V <sub>CC</sub>				±1		
			V <sub>I</sub> = 0.2 V				–10 –20		
I <sub>off</sub>	Leakage current	SDA <sub>x</sub> , SCL <sub>x</sub>	V <sub>I</sub> = 3.6 V	EN = L or H	0 V		0.5	μA	
			V <sub>I</sub> = GND				0.5		
I <sub>I(ramp)</sub>	Leakage current during power up	SDA <sub>x</sub> , SCL <sub>x</sub>	V <sub>I</sub> = 3.6 V	EN = L or H	0 V to 2.3 V		1	μA	
C <sub>in</sub>	Input capacitance	EN	V <sub>I</sub> = 3 V or GND	EN = H	3.3 V		7	9	pF
		SDA <sub>x</sub> , SCL <sub>x</sub>			3.3 V		7	9	

(1) All typical values are at nominal supply voltage (V<sub>CC</sub> = 2.5 V or 3.3 V) and T<sub>A</sub> = 25°C.

## 6.5 Timing Requirements

over recommended operating free-air temperature range (unless otherwise noted) (see [Figure 1](#))

		V <sub>CC</sub> = 2.5 V ± 0.2 V		V <sub>CC</sub> = 3.3 V ± 0.3 V		UNIT
		MIN	MAX	MIN	MAX	
t <sub>su</sub>	Setup time, EN↑ before Start condition	100		100		ns
t <sub>h</sub>	Hold time, EN↓ after Stop condition	130		100		ns

## 6.6 Switching Characteristics

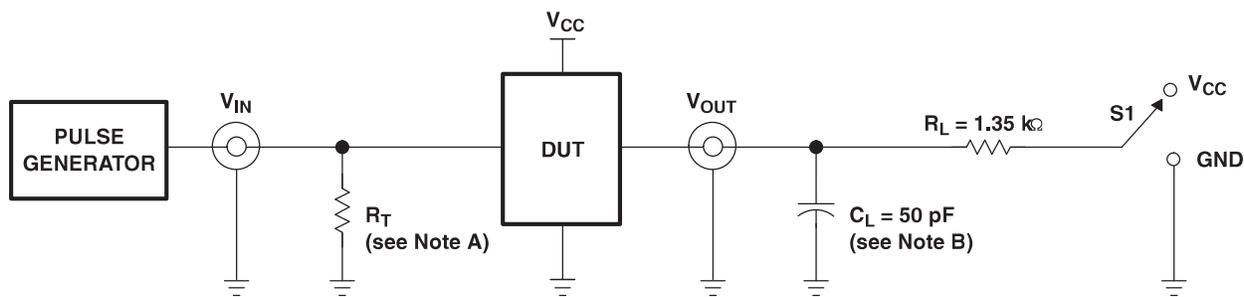
over recommended operating free-air temperature range, C<sub>L</sub> ≤ 100 pF (unless otherwise noted)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub> = 2.5 V ± 0.2 V			V <sub>CC</sub> = 3.3 V ± 0.3 V			UNIT
			MIN	TYP <sup>(1)</sup>	MAX	MIN	TYP <sup>(1)</sup>	MAX	
t <sub>PZL</sub>	Propagation delay time <sup>(2)</sup>	SDA0, SCL0 or SDA1, SCL1	45	82	130	45	68	120	ns
t <sub>PLZ</sub>									
t <sub>HL</sub>	Output transition time <sup>(2)</sup> (SDA <sub>x</sub> , SCL <sub>x</sub> )	80%	20%	57	58	147	ns		
t <sub>LH</sub>		20%						80%	148

(1) All typical values are at nominal supply voltage (V<sub>CC</sub> = 2.5 V or 3.3 V) and T<sub>A</sub> = 25°C.

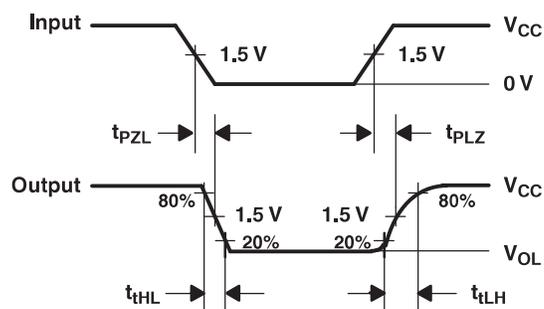
(2) Different load resistance and capacitance alter the RC time constant, thereby changing the propagation delay and transition times.

## 7 Parameter Measurement Information



TEST	S1
$t_{PLZ}/t_{PZL}$	$V_{CC}$

TEST CIRCUIT FOR OPEN-DRAIN OUTPUT



VOLTAGE WAVEFORMS  
PROPAGATION DELAY AND OUTPUT TRANSITION TIMES

- A.  $R_T$  termination resistance should be equal to  $Z_{OUT}$  of pulse generators.
- B.  $C_L$  includes probe and jig capacitance.
- C. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 10$  MHz,  $Z_O = 50 \Omega$ , slew rate  $\geq 1$  V/ns.
- D. The outputs are measured one at a time, with one transition per measurement.
- E.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .
- F.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
- G.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .

Figure 1. Test Circuit and Voltage Waveforms

## 8 Detailed Description

### 8.1 Functional Block Diagram

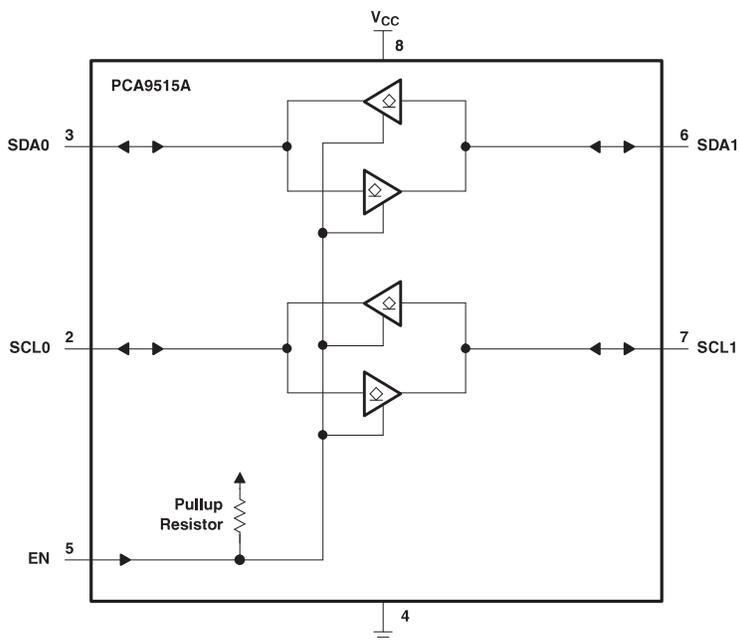


Figure 2. Logic Diagram (Positive Logic)

### 8.2 Feature Description

#### 8.2.1 Clock Stretching Errata

##### Description

Due to the static offset on both sides of the buffer (SCLx & SDAx) and the possibility of an overshoot above 500 mV during events like clock stretching, the device should not be used with rise time accelerators.

##### System Impact

An incorrect logic state will be passed through the buffer, creating an I2C communication failure on the bus.

##### System Workaround

There is a possible workaround to avoid an I2C communication failure:

- Do not use rise-time accelerators in conjunction with the PCA9515A.

### 8.3 Device Functional Modes

Table 1. Function Table

INPUT EN	FUNCTION
L	Outputs disabled
H	SDA0 = SDA1 SCL0 = SCL1